

MECHANICAL CASE OUTLINE

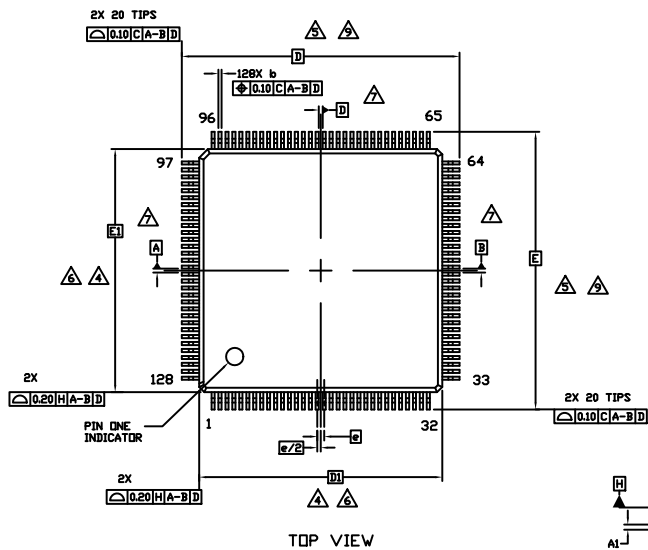
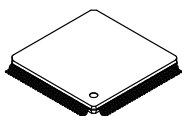
PACKAGE DIMENSIONS

ON Semiconductor®

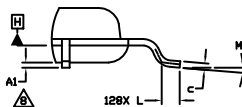


TQFP128 14x14 / TQFP128L
CASE 932BA
ISSUE A

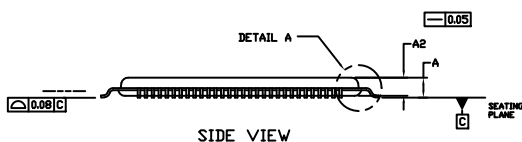
DATE 30 APR 2015



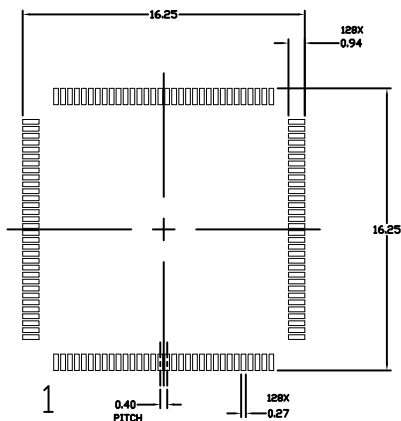
TOP VIEW



DETAIL A



SIDE VIEW



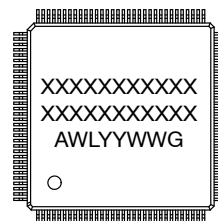
RECOMMENDED MOUNTING FOOTPRINT

NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS
- DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL BE 0.08 MAX. AT MMC. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD IS 0.07.
- DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.25 PER SIDE. DIMENSIONS D1 AND E1 ARE MAXIMUM PLASTIC BODY SIZE INCLUDING MOLD MISMATCH.
- THE TOP PACKAGE BODY SIZE MAY BE SMALLER THAN THE BOTTOM PACKAGE SIZE BY AS MUCH AS 0.15.
- DIMENSIONS D1 AND E1 TO BE DETERMINED AT DATUM PLANE H.
- DATUMS A-B AND D ARE DETERMINED AT DATUM PLANE H.
- A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
- DIMENSIONS D AND E TO BE DETERMINED AT DATUM PLANE C.

DIM	MILLIMETERS	
	MIN.	MAX.
A	---	1.20
A1	0.05	0.15
A2	1.00 REF	
b	0.13	0.23
c	0.09	0.20
D	16.00 BSC	
D1	14.00 BSC	
E	16.00 BSC	
E1	14.00 BSC	
e	0.40 BSC	
L	0.45	0.75
M	0°	7°

GENERIC MARKING DIAGRAM*



- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present.

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